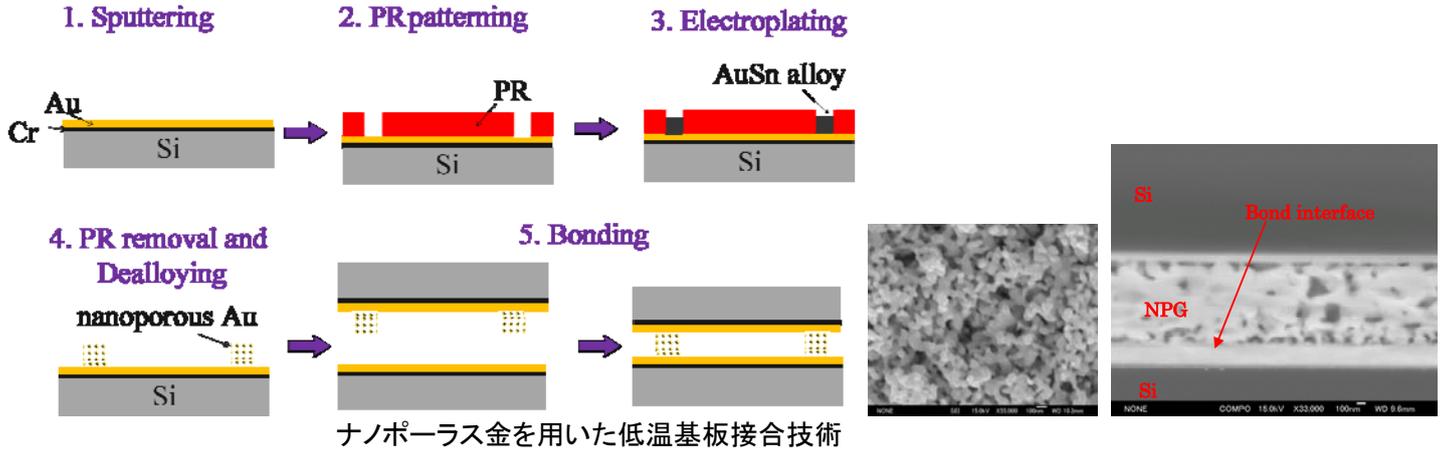
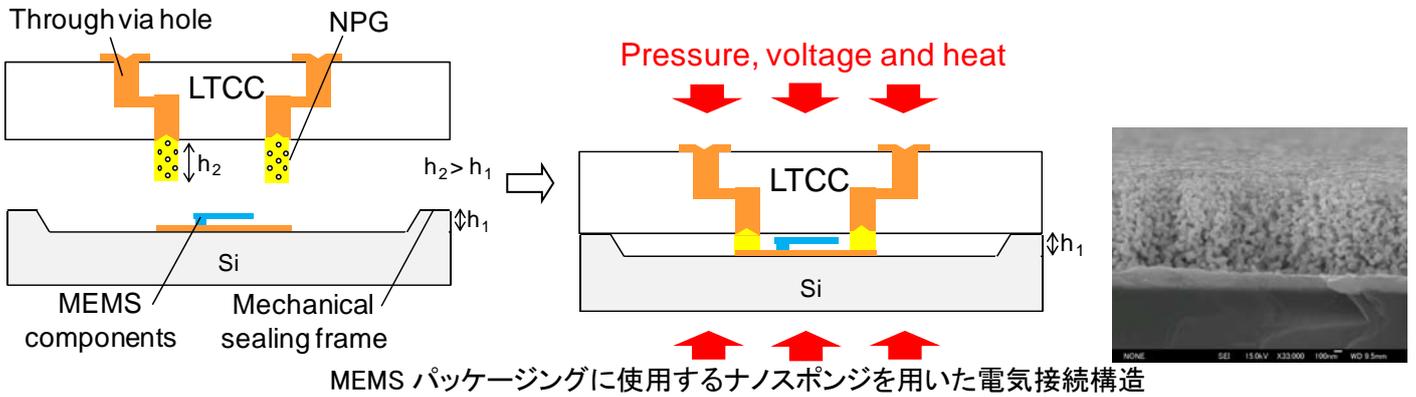


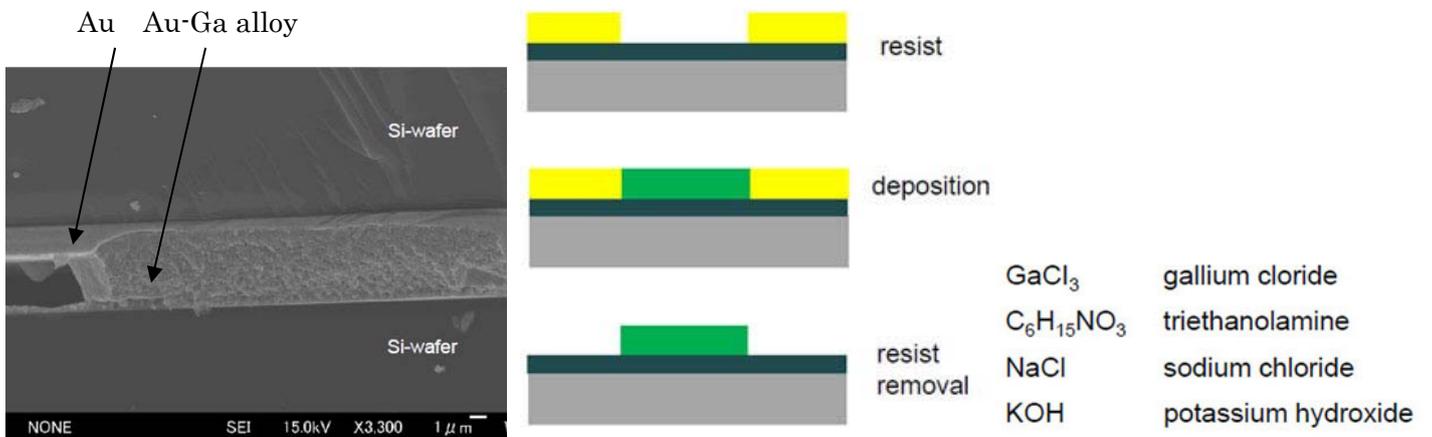
接合材料 (WPI-AIMR, フラウンホーファ ENAS - 東北大)



参考文献 : W. -S. Wang, Y. -C. Lin, L. Y. Chen, M. W. Chen, T. Gessner and M. Esashi, Demonstration of Substrate Bonding utilizing Au Film and Nanoporous Gold Structures, Proceedings of the International Conference on Wafer Bond ' 11, Dec. 7-8 (2011)



参考文献 : Y. -C. Lin, W. -S. Wang, L. Y. Chen, M. W. Chen, T. Gessner and M. Esashi, Anodically-bondable LTCC substrates with Novel nano-structured electrical Interconnection for mems packaging, Proceedings of the international conference on solid-state sensors and actuators (Transducers ' 11), June 5-9 (2011) pp. 2351-2354



Ga を用いた室温 SLID (Solid-Liquid Inter-Diffusion bonding) (左:接合断面、右 Ga めっき)

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